1.0 SCOPE

This Application Specification covers the CMC 48/36 and 72/96 WAY ECU HEADER assembly operation on PC Board and Recommended enclosure system for the Header.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER (S)

<table>
<thead>
<tr>
<th>PRODUCT NAME</th>
<th>SERIES NUMBER</th>
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<tbody>
<tr>
<td>CMC WAY HEADER X 1 T3 INTERFACE</td>
<td>36638</td>
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3.0 REFERENCE DOCUMENT:

See the appropriate customer drawings SD-36638-002/003 for information on dimensions, materials, markings and part numbers.

4.0 ASSEMBLY PROCEDURE

4.1 COMPONENT GRIPPING (Shown 48/36 way only):

- Take in one hand the CMC Header Assembly with soldering ends oriented upwards,

- Take in one hand the PC Board, appropriate holes located in front of the header pins.
4.2 PC BOARD POSITIONING:

- Place the PC Board over the CMC header aligning to the Header Pin Positions. Press gently and make sure that the header locking pegs are well inserted in the PC Board holes, as shown below.

4.3 PC BOARD LOCKING:

- Ensure complete locking of the Header locking pegs. Check that the two locking latches are fully locked as shown below.
5.0 RECOMMENDED CASING DESIGN CONCEPTS ***:

5.1 CONCEPT 1:

-In this design first the header is fitted to the casing body and then PCB can be mounted to the header and closed as shown below in the assembly steps:

*** - Note that this is a basic concept and is not dimensioned to the actual requirement and also the casing material and design can be as per the customer feasibility.
5.2 CONCEPT 2:

- In this design first the header can be mounted and locked on to the PCB, assembly of PCB with Header can be inserted in to the casing with seals and top cover is closed as shown below.

*** - Note that this is a basic concept and is not dimensioned to the actual requirement and also the casing material and design can be as per the customer feasibility.
6.0 ADHESIVE SEALING GUIDELINES

- Guidelines to be used for adhesive sealants as used in sealing between Header and Plastic Modules/Covers.
- Molex does not provide the seal. Customer to get it sourced.

6.1 GENERAL REQUIREMENTS

For geometry information see appropriate product specifications.

Material: silicone

Performance Characteristics:
- Elongation
  ES > DC, DB, DH
  Sealant: ES
  Deformation Amount of Cover: DC
  Deformation Amount of Base: DB
  CMC Header: DH (=3x10^-6 mm/Co)
- Heat Resistance
- Chemical Resistance
- Siloxane Content

Process Characteristics:
- Viscosity
- Cure type (RTV, UV and Heat Cure) and temperatures.